

74AHCT240-Q100

Octal buffer/line driver; inverting; 3-state

Rev. 2 — 1 March 2016

Product data sheet

1. General description

The 74AHCT240-Q100 is an 8-bit inverting buffer/line drivers with 3-state outputs. This device can be used as two 4-bit buffers or one 8-bit buffer. It features two output enables ($\overline{1OE}$ and $\overline{2OE}$), each controlling four of the 3-state outputs. A HIGH on \overline{nOE} causes the outputs to assume a high-impedance OFF-state. Inputs are over voltage tolerant. This feature allows the use of these devices as translators in mixed voltage environments.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Balanced propagation delays
- All inputs have a Schmitt-trigger action
- Inputs accept voltages higher than V_{CC}
- 74AHCT240-Q100 operates with TTL input levels
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
- Multiple package options



3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AHCT240D-Q100	-40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74AHCT240PW-Q100	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74AHCT240BQ-Q100	-40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

4. Functional diagram

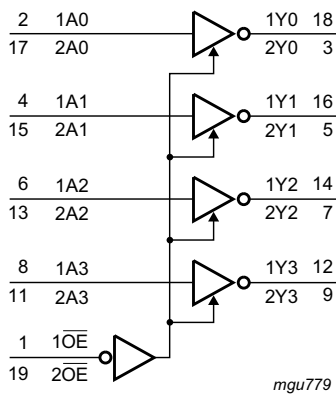


Fig 1. Logic symbol

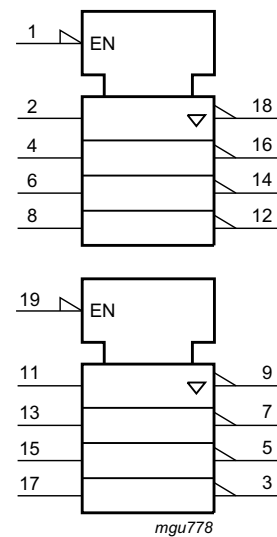
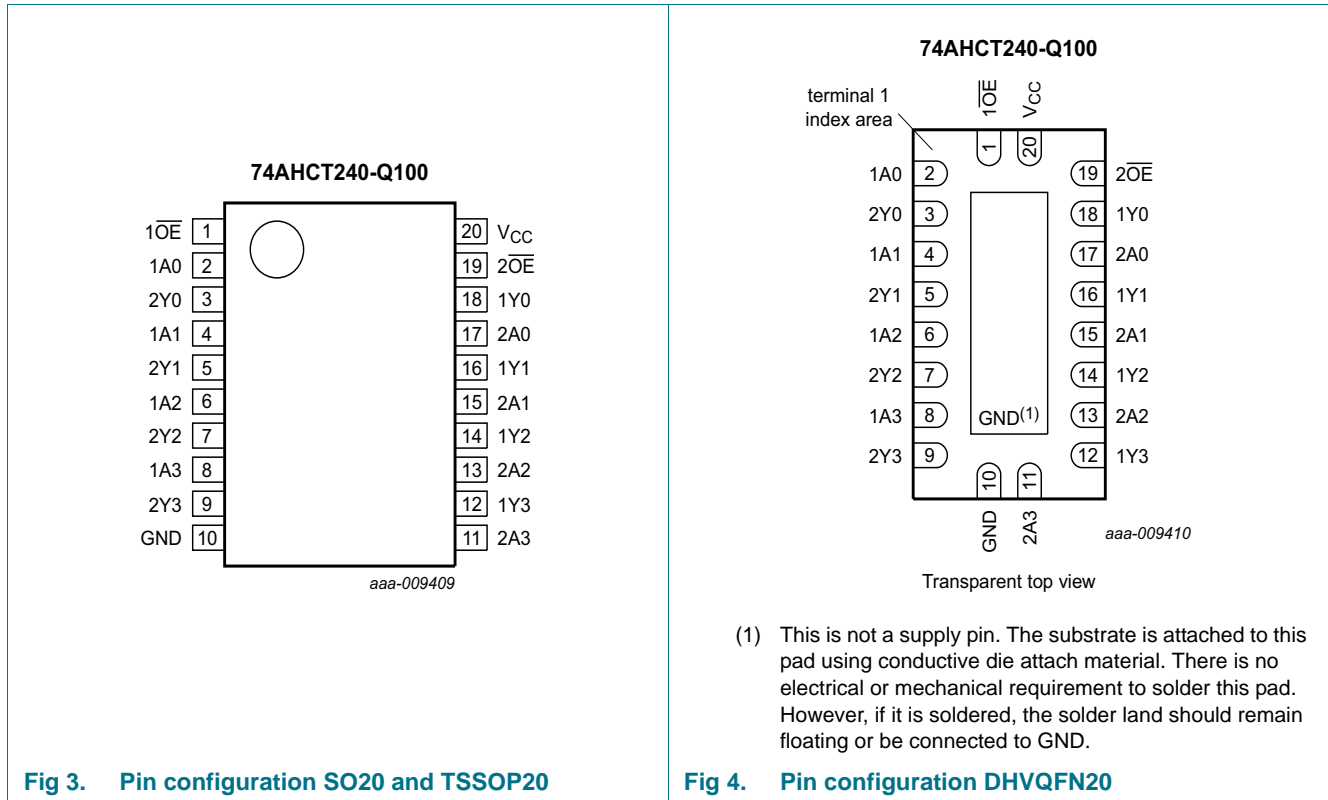


Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE	1	output enable input (active LOW)
2OE	19	output enable input (active LOW)
1A0, 1A1, 1A2, 1A3	2, 4, 6, 8	data input
2A0, 2A1, 2A2, 2A3	17, 15, 13, 11	data input
1Y0, 1Y1, 1Y2, 1Y3	18, 16, 14, 12	data output
2Y0, 2Y1, 2Y2, 2Y3	3, 5, 7, 9	data output
GND	10	ground (0 V)
VCC	20	power supply

6. Functional description

Table 3. Function table^[1]

Control	Input	Output
nOE	nAn	nYn
L	L	H
L	H	L
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
V _I	input voltage		-0.5	+7.0	V
I _{IK}	input clamping current	V _I < -0.5 V ^[1]	-20	-	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V ^[1]	-	±20	mA
I _O	output current	V _O = -0.5 V to (V _{CC} + 0.5 V)	-	±25	mA
I _{CC}	supply current		-	75	mA
I _{GND}	ground current		-75	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C ^[2]	-	500	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO20 package: above 70 °C the value of P_{tot} derates linearly with 8.0 mW/K.
 For TSSOP20 package: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.
 For DHVQFN20 package: above 60 °C the value of P_{tot} derates linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage		4.5	5.0	5.5	V
V _I	input voltage		0	-	5.5	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 5 V ± 0.5 V	-	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = -50 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -8.0 mA	3.94	-	-	3.80	-	3.70	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = 50 μA	-	0	0.1	-	0.1	-	0.1	V
		I _O = 8.0 mA	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND per input pin; other inputs at V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	±0.25	-	±2.5	-	±10.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	4.0	-	40	-	80	μA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} - 2.1 V; other pins at V _{CC} or GND; I _O = 0 A; V _{CC} = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C _I	input capacitance	V _I = V _{CC} or GND	-	3	10	-	10	-	10	pF
C _O	output capacitance		-	4	-	-	-	-	-	pF

10. Dynamic characteristics

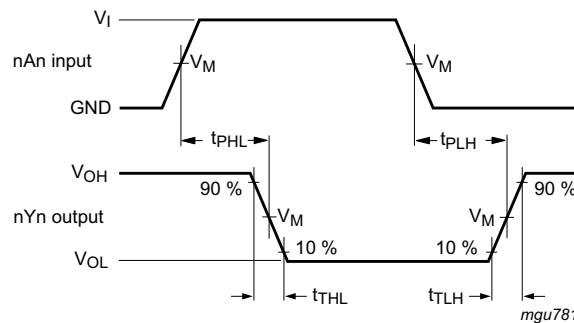
Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit, see [Figure 7](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Max (125 °C)	
t _{pd}	propagation delay	nAn to nYn; see Figure 5 ^[2]							
		V _{CC} = 4.5 V to 5.5 V; C _L = 15 pF	-	3.0	5.8	1.0	6.8	8.5	ns
		V _{CC} = 4.5 V to 5.5 V; C _L = 50 pF	-	4.4	8.4	1.0	9.5	11.9	ns
t _{en}	enable time	n $\overline{O}E$ to nYn; see Figure 6 ^[2]							
		V _{CC} = 4.5 V to 5.5 V; C _L = 15 pF	-	3.4	7.5	1.0	9.0	14.4	ns
		V _{CC} = 4.5 V to 5.5 V; C _L = 50 pF	-	4.5	9.5	1.0	11.5	14.4	ns
t _{dis}	disable time	n $\overline{O}E$ to nYn; see Figure 6 ^[2]							
		V _{CC} = 4.5 V to 5.5 V; C _L = 15 pF	-	3.9	6.1	1.0	6.7	8.3	ns
		V _{CC} = 4.5 V to 5.5 V; C _L = 50 pF	-	6.2	8.7	1.0	9.2	11.5	ns
C _{PD}	power dissipation capacitance	V _I = GND to V _{CC} ; C _L = 50 pF; f _i = 1 MHz ^[3]	-	9	-	-	-	-	pF

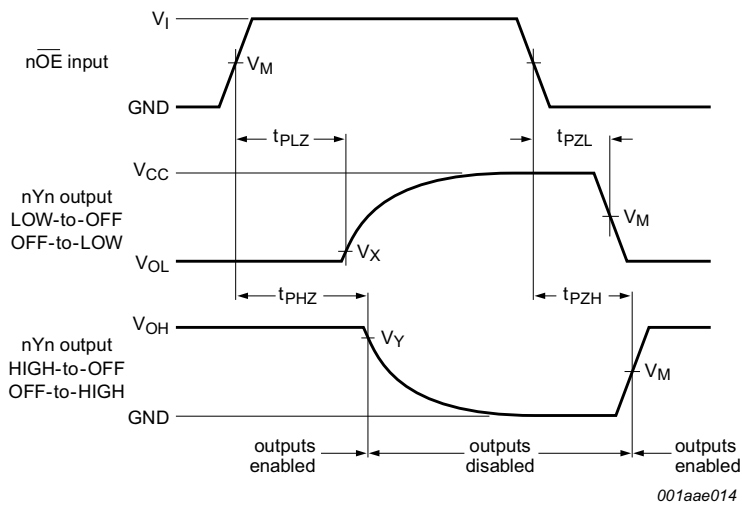
- [1] Typical values are measured at nominal supply voltage (V_{CC} = 5.0 V).
- [2] t_{pd} is the same as t_{PLH} and t_{PHL}; t_{en} is the same as t_{PZH} and t_{PZL}; t_{dis} is the same as t_{PLZ} and t_{PHZ}.
- [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 $\sum(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Propagation delay input (nAn) to output (nYn)

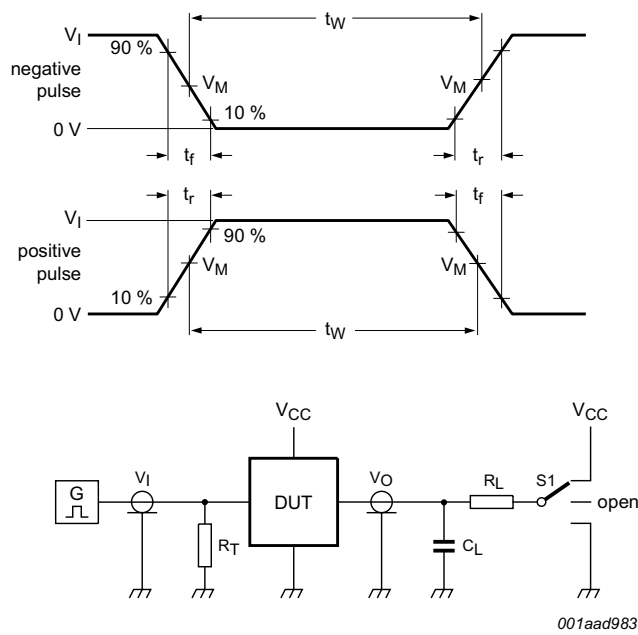


Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Enable and disable times

Table 8. Measurement points

Input	Output		
V_M	V_M	V_X	V_Y
1.5 V	$0.5V_{CC}$	$V_{OL} + 0.3 V$	$V_{OH} - 0.3 V$



Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 7. Test circuit for measuring switching times

Table 9. Test data

Input		Load		S1 position		
V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
3.0 V	3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

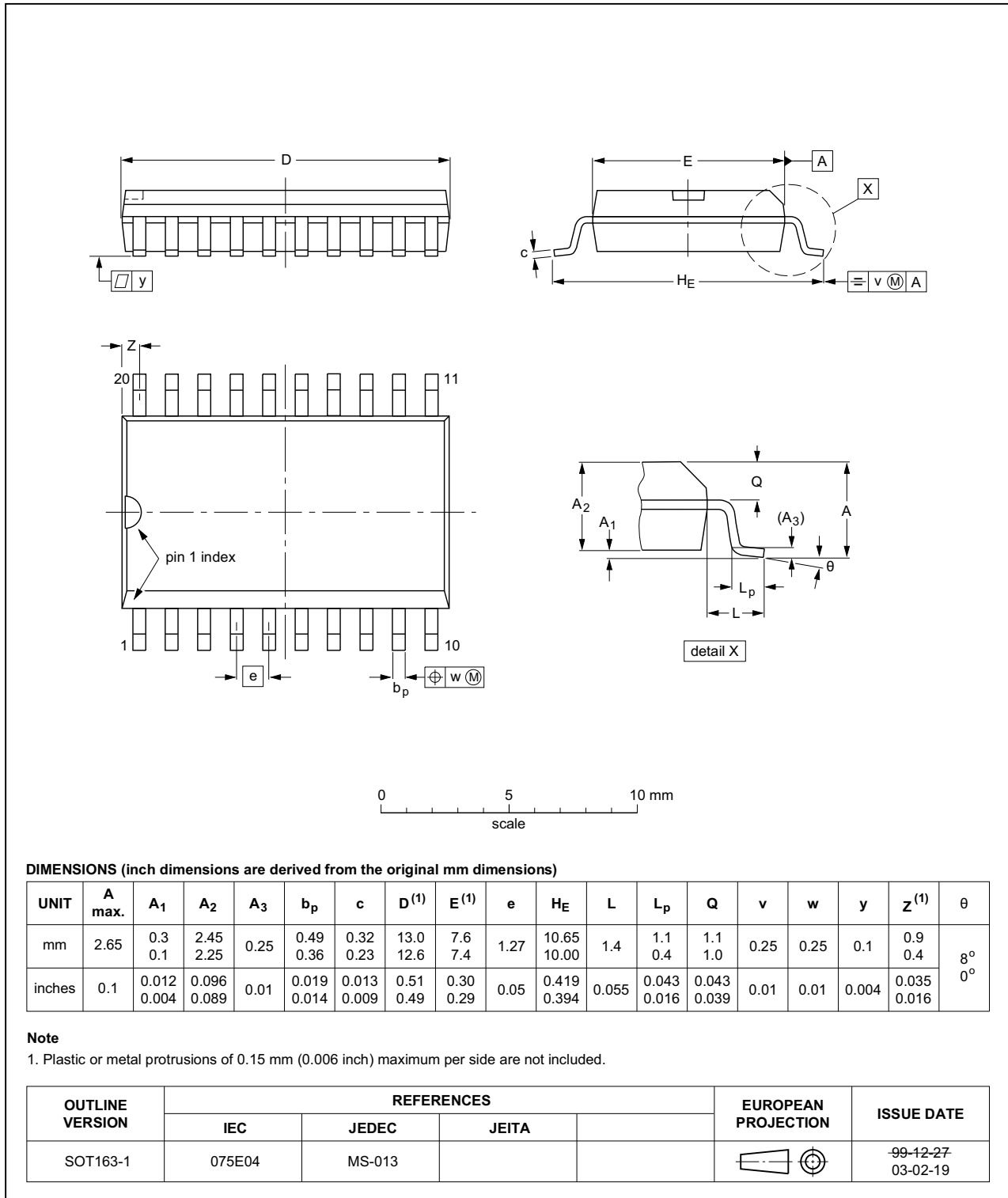


Fig 8. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

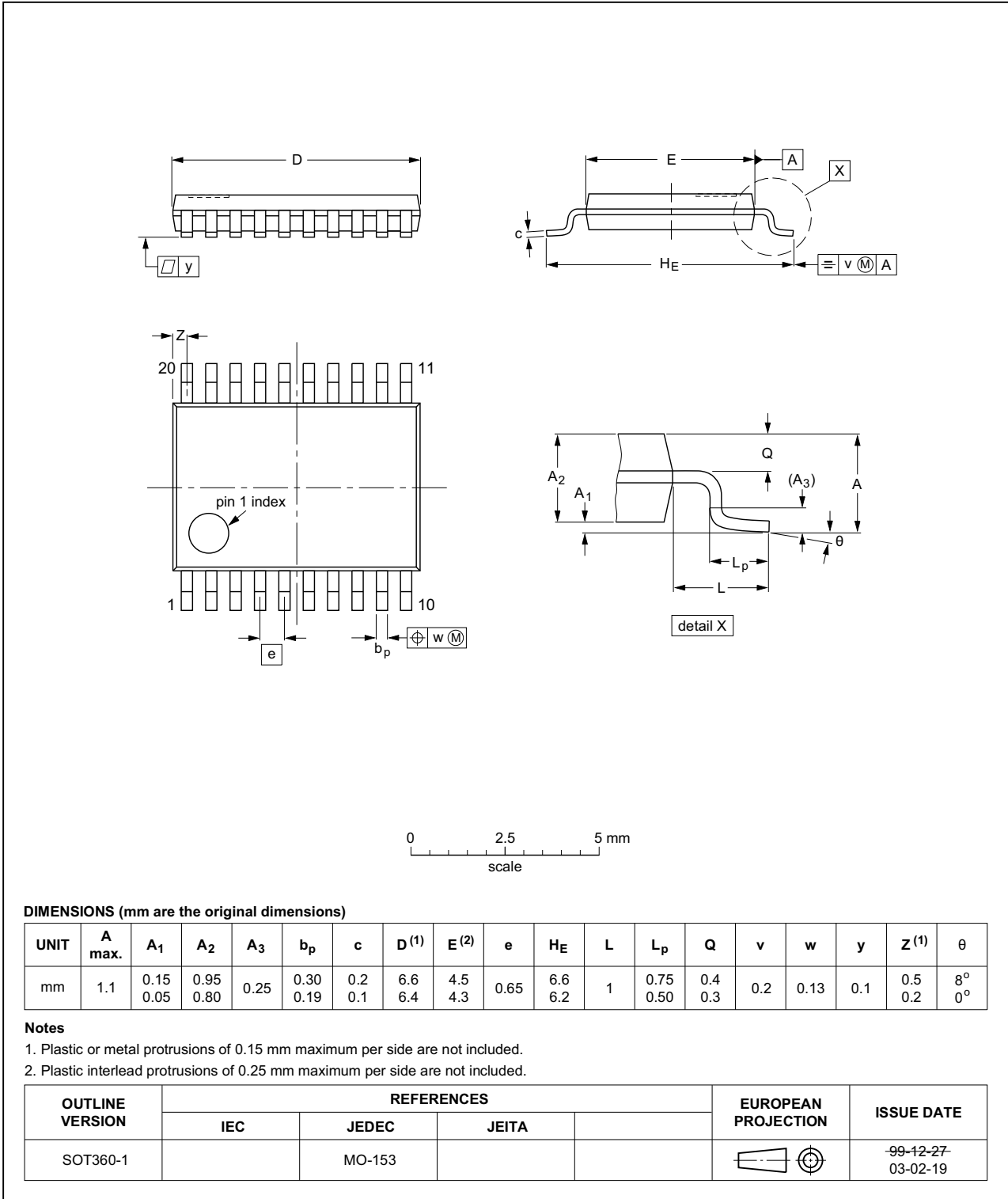


Fig 9. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

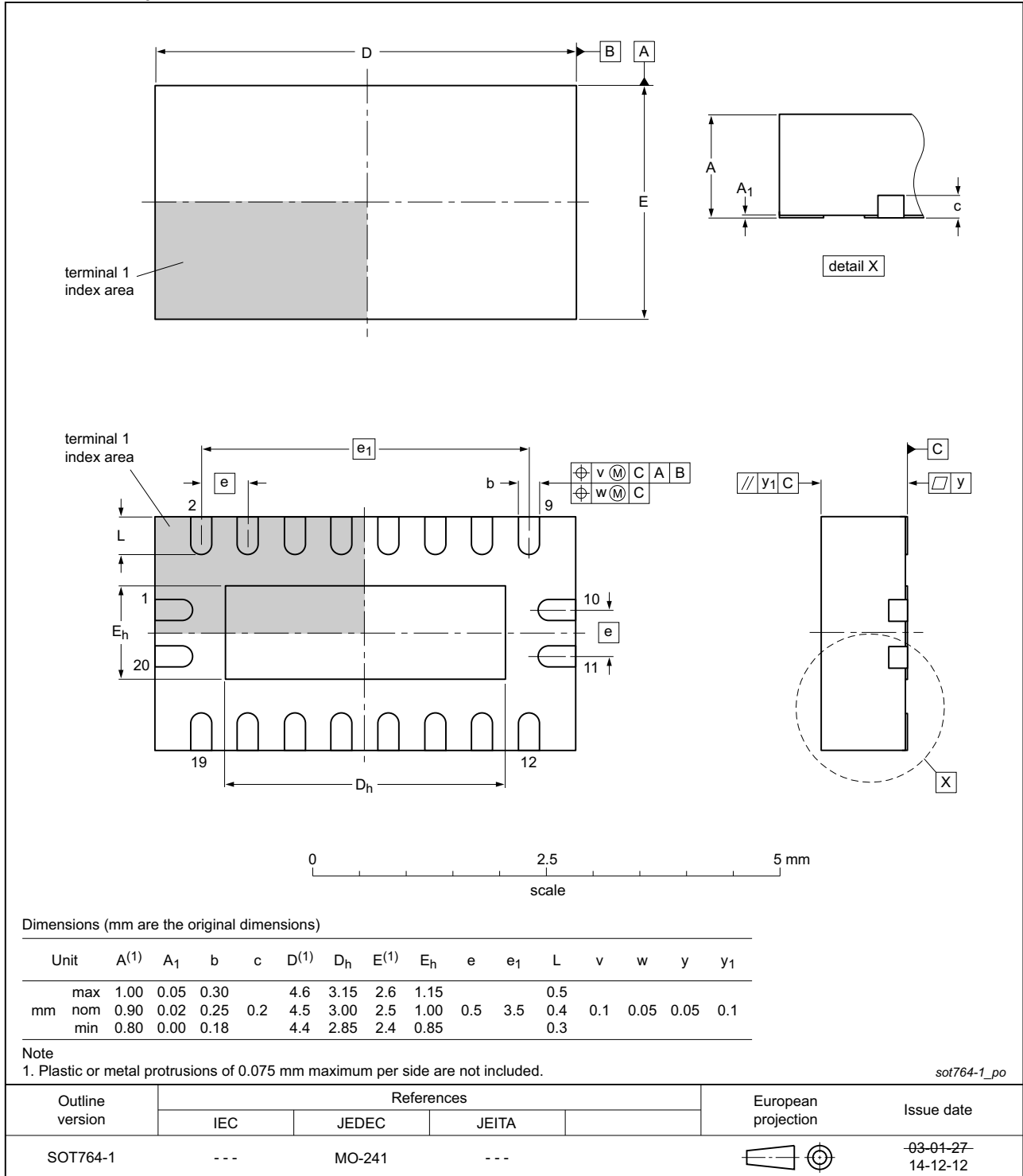


Fig 10. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charge Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
MIL	Military
HBM	Human Body Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHCT240_Q100 v.2	20160301	Product data sheet	-	74AHC_AHCT240_Q100 v.1
Modifications:	<ul style="list-style-type: none"> Type numbers 74AHC240D-Q100, 74AHC240PW-Q100 and 74AHC240BQ-Q100 removed. 			
74AHC_AHCT240_Q100 v.1	20131106	Product data sheet	-	-

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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